

Sharon Nai

List of Publications by Year in descending order

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69
papers

1,857
citations

279701

23
h-index

265120

42
g-index

69
all docs

69
docs citations

69
times ranked

1198
citing authors

#	ARTICLE	IF	CITATIONS
1	Improving the performance of lead-free solder reinforced with multi-walled carbon nanotubes. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2006, 423, 166-169.	2.6	139
2	Interfacial intermetallic growth and shear strength of lead-free composite solder joints. <i>Journal of Alloys and Compounds</i> , 2009, 473, 100-106.	2.8	135
3	Influence of ceramic reinforcements on the wettability and mechanical properties of novel lead-free solder composites. <i>Thin Solid Films</i> , 2006, 504, 401-404.	0.8	127
4	Low temperature wafer anodic bonding. <i>Journal of Micromechanics and Microengineering</i> , 2003, 13, 217-222.	1.5	125
5	Spatial and geometrical-based characterization of microstructure and microhardness for an electron beam melted Ti-6Al-4V component. <i>Materials and Design</i> , 2016, 95, 287-295.	3.3	112
6	Effect of Carbon Nanotubes on the Shear Strength and Electrical Resistivity of a Lead-Free Solder. <i>Journal of Electronic Materials</i> , 2008, 37, 515-522.	1.0	103
7	Microhardness and microstructure evolution of TiB ₂ reinforced Inconel 625/TiB ₂ composite produced by selective laser melting. <i>Optics and Laser Technology</i> , 2016, 80, 186-195.	2.2	101
8	Effect of carbon nanotubes on corrosion of Mg-CNT composites. <i>Corrosion Science</i> , 2010, 52, 1551-1553.	3.0	82
9	Interfacial reaction and shear strength of Ni-coated carbon nanotubes reinforced Sn-Ag-Cu solder joints during thermal cycling. <i>Intermetallics</i> , 2012, 31, 72-78.	1.8	75
10	Development of a Sn-Ag-Cu solder reinforced with Ni-coated carbon nanotubes. <i>Journal of Materials Science: Materials in Electronics</i> , 2011, 22, 315-322.	1.1	74
11	Temperature Dependence of Creep and Hardness of Sn-Ag-Cu Lead-Free Solder. <i>Journal of Electronic Materials</i> , 2010, 39, 223-229.	1.0	58
12	Reinforcements at nanometer length scale and the electrical resistivity of lead-free solders. <i>Journal of Alloys and Compounds</i> , 2009, 478, 458-461.	2.8	51
13	Development of lead-free Sn-3.5Ag/SnO ₂ nanocomposite solders. <i>Journal of Materials Science: Materials in Electronics</i> , 2009, 20, 571-576.	1.1	49
14	Characterization of nanoparticle mixed 316L powder for additive manufacturing. <i>Journal of Materials Science and Technology</i> , 2020, 47, 162-168.	5.6	48
15	Development of high strength Sn-Cu solder using copper particles at nanolength scale. <i>Journal of Alloys and Compounds</i> , 2009, 476, 199-206.	2.8	47
16	Using Microwave-Assisted Powder Metallurgy Route and Nano-size Reinforcements to Develop High-Strength Solder Composites. <i>Journal of Materials Engineering and Performance</i> , 2010, 19, 335-341.	1.2	43
17	Enhanced welding efficiency in laser welding of highly reflective pure copper. <i>Journal of Materials Processing Technology</i> , 2015, 216, 287-293.	3.1	41
18	Micro-structure and Mechanical Properties of Nano-TiC Reinforced Inconel 625 Deposited using LAAM. <i>Physics Procedia</i> , 2013, 41, 828-834.	1.2	37

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19	DFT Study on Nano Structures of Sn/CNT Complex for Potential Li-Ion Battery Application. Journal of Physical Chemistry C, 2009, 113, 14015-14019.	1.5	33
20	Using carbon nanotubes to enhance creep performance of lead free solder. Materials Science and Technology, 2008, 24, 443-448.	0.8	30
21	Glass-to-glass anodic bonding process and electrostatic force. Thin Solid Films, 2004, 462-463, 487-491.	0.8	28
22	Low temperature glass-to-glass wafer bonding. IEEE Transactions on Advanced Packaging, 2003, 26, 289-294.	1.7	24
23	Effect of Building Height on Microstructure and Mechanical Properties of Big-Sized Ti-6Al-4V Plate Fabricated by Electron Beam Melting. MATEC Web of Conferences, 2015, 30, 02001.	0.1	24
24	A modified constitutive model for creep of Sn-3.5Ag-0.7Cu solder joints. Journal Physics D: Applied Physics, 2009, 42, 125411.	1.3	23
25	Synthesis and wear characterization of Al based, free standing functionally graded materials: effects of different matrix compositions. Composites Science and Technology, 2003, 63, 1895-1909.	3.8	22
26	Effect of Ni-Coated Carbon Nanotubes on Interfacial Reaction and Shear Strength of Sn-Ag-Cu Solder Joints. Journal of Electronic Materials, 2012, 41, 2478-2486.	1.0	21
27	Synthesis of Al/SiC based functionally gradient materials using technique of gradient slurry disintegration and deposition: effect of stirring speed. Materials Science and Technology, 2002, 18, 633-641.	0.8	20
28	Influence of applied load on vacuum wafer bonding at low temperature. Sensors and Actuators A: Physical, 2004, 115, 67-72.	2.0	17
29	Effect of Ni-Coated Carbon Nanotubes on the Corrosion Behavior of Sn-Ag-Cu Solder. Journal of Electronic Materials, 2013, 42, 3559-3566.	1.0	15
30	Synthesis and wear of Al based, free standing functionally gradient materials: effects of different reinforcements. Materials Science and Technology, 2004, 20, 57-67.	0.8	14
31	Effect of Amount of Cu on the Intermetallic Layer Thickness Between Sn-Cu Solders and Cu Substrates. Journal of Electronic Materials, 2009, 38, 2479-2488.	1.0	12
32	INDENTATION SIZE EFFECT ON THE CREEP BEHAVIOR OF A SnAgCu SOLDER. International Journal of Modern Physics B, 2010, 24, 267-275.	1.0	12
33	Kinetics of interface reaction and intermetallics growth of Sn-3.5Ag-0.7Cu/Au/Ni/Cu system under isothermal aging. Journal of Materials Science, 2004, 39, 1095-1099.	1.7	11
34	DEVELOPMENT OF NOVEL LEAD-FREE SOLDER COMPOSITES USING CARBON NANOTUBE REINFORCEMENTS. International Journal of Nanoscience, 2005, 04, 423-429.	0.4	11
35	Development of Lead-Free Solder Composites Containing Nanosized Hybrid (ZrO ₂ ; + 8 mol.% Y ₂ O ₃) Particulates. Solid State Phenomena, 2006, 111, 59-62.	0.3	10
36	Synthesis and characterization of free standing, bulk Al/SiCp functionally gradient materials: effects of different stirrer geometries. Materials Research Bulletin, 2003, 38, 1573-1589.	2.7	9

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37	Silicon-to-silicon wafer bonding with gold as intermediate layer. , 0, , .		9
38	Microstructure and damping characteristics of Mg and its composites containing metastable Al ₈₅ Ti ₁₅ particle. Journal of Composite Materials, 2016, 50, 2565-2573.	1.2	8
39	Advanced high density interconnect materials and techniques. , 2009, , .		7
40	Comparative Eco-efficiency Analyses of Copper to Copper Bonding Technologies. Procedia CIRP, 2014, 15, 96-104.	1.0	6
41	Integrating copper at the nanometer length scale with Sn ³ Ag solder to develop high performance nanocomposites. Materials Science and Technology, 2009, 25, 1258-1264.	0.8	5
42	Enhancing the properties of a lead-free solder with the addition of Ni-coated carbon nanotubes. , 2009, , .		5
43	NANOMECHANICAL PROPERTIES OF A Sn ³ Ag ³ Cu SOLDER REINFORCED WITH Ni-COATED CARBON NANOTUBES. International Journal of Nanoscience, 2010, 09, 283-287.	0.4	5
44	Low-temperature sol ³ gel intermediate layer wafer bonding. Thin Solid Films, 2006, 496, 560-565.	0.8	4
45	Suppressing intermetallic compound growth in SnAgCu solder joints with addition of carbon nanotubes. , 2008, , .		4
46	Effect of Ni-coated carbon nanotubes on the microstructure and properties of a Sn-Ag-Cu solder. , 2010, , .		3
47	Influence of plasma treatment and cleaning on vacuum wafer bonding. , 0, , .		2
48	Enhancing the Performance of Sn-Ag-Cu Solder With the Addition of Titanium Diboride Particulates. , 2004, , 315.		2
49	Influence of Reinforcements on the Electrical Resistivity of Novel Sn-Ag-Cu Composite Solder. , 2007, , 39.		2
50	Development of Lead-Free Nanocomposite Solders Using Oxide Based Reinforcement. , 2008, , .		2
51	Effect of Presence of Multi-Walled Carbon Nanotubes on the Creep Properties of Sn-Ag-Cu Solder. , 2006, , 161.		1
52	A New Creep Model for SnAgCu Lead-Free Composite Solders: Incorporating Back Stress. , 2008, , .		1
53	Development of Al and Al/Cu (composite/alloy) formulations with enhanced properties through microwave power variations during hybrid sintering. Journal Physics D: Applied Physics, 2008, 41, 175401.	1.3	1
54	Effect of Ni-coated carbon nanotubes on interfacial intermetallic layer growth. , 2009, , .		1

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55	Utilizing energy efficient microwave sintering to significantly enhance the tensile response of a lead-free solder. Journal Physics D: Applied Physics, 2009, 42, 015404.	1.3	1
56	Indentation Size Effect on the Hardness of a Sn-Ag-Cu Solder. , 2009, , .		1
57	Ageing study of interfacial intermetallic growth in a lead-free solder reinforced with Ni-coated carbon nanotubes. , 2010, , .		1
58	Indentation creep and hardness of a Sn-Ag-Cu solder reinforced with Ni-coated carbon nanotubes. , 2010, , .		1
59	Enhanced Mechanical Properties of Poly(Vinyl Alcohol) Nanofibers With Molecular Level Dispersed Graphene. , 2012, , .		1
60	Development of Advanced Lead-Free Solder Based Interconnect Materials Containing Nanosized Y2O3 Particulates. , 2005, , .		1
61	Silicon-to-silicon wafer bond efficiency by sol-gel process. , 0, , .		0
62	Wafer Level Packaging of RF MEMS for Flip Chip Assembly. , 2003, , 119.		0
63	Low Temperature Wafer Bonding Process Using Sol-Gel Intermediate Layer. , 2004, , 309.		0
64	Enhancement of Mechanical Properties by Reinforcing Magnesium With Ni-Coated Carbon Nanotubes. , 2010, , .		0
65	Thermal Management for High Power Light-Emitting Diode Street Lamp. , 2010, , .		0
66	Influence of Bonding Pressure on the Mechanical Properties of Copper Bumps. , 2012, , .		0
67	Effect of Nano-Size Oxide Based Reinforcement on the Tensile Properties of Sn-Ag-Cu Solder. , 2008, , .		0
68	Solder Joint Technology. , 2015, , 713-763.		0
69	Solid State Microjoining Processes in Manufacturing. , 2015, , 641-683.		0